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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1 – 14 (canceled).

Claim 15 (currently amended): A leadless plastic chip carrier comprising:

a die attach pad;

at least one semiconductor die mounted on said die attach pad;

a plurality of contact pads circumscribing and offset from said die attach pad;

a plurality of wire bonds connecting said at least one semiconductor die and various ones of said contact pads; and

an overmold covering said semiconductor die and all except one surface of each of said contact pads such that said overmold substantially lies in a plane from which said die attach pad protrudes and from which said contact pads do not protrude;

~~wherein said die attach pad is offset from said contact pads such that said die attach pad protrudes from said molding compound.~~

Claim 16 (original): The leadless plastic chip carrier according to claim 15, further comprising a plurality of solder balls disposed on said contact pads.

Claim 17 (original): The leadless plastic chip carrier according to claim 15, further comprising a ground ring on a periphery of said die attach pad, said plurality of wire bonds further comprising wire bonds connecting said semiconductor die and said ground ring.

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Claim 18 (original): The leadless plastic chip carrier according to claim 15, further comprising a power ring intermediate said contact pads and said die attach pad, said plurality of wire bonds further comprising wire bonds connecting said semiconductor die and said power ring.

Claim 19 (original): The leadless plastic chip carrier according to claim 15, wherein said at least one semiconductor die comprises a plurality of semiconductor dice stacked on top of each other and said plurality of wire bonds comprises wire bonds connecting ones of said plurality of semiconductor dice and ones of said contact pads.

Claim 20 (original): The leadless plastic chip carrier according to claim 19, wherein adjacent ones of said semiconductor dice are separated by a layer of epoxy.

Claim 21 (original): The leadless plastic chip carrier according to claim 19, further comprising a plurality of solder balls disposed on said contact pads.

Claim 22 (original): The leadless plastic chip carrier according to claim 15, wherein said die attach pad comprises a plurality of layers of metal.

Claim 23 (original): The leadless plastic chip carrier according to claim 15, wherein said contact pads comprise a plurality of layers of metal.

Claim 24 (original): The leadless plastic chip carrier according to claim 22, wherein said plurality of layers of metal includes layers of gold, nickel and copper, or silver and copper, or palladium, nickel and copper.

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Claim 25 (original): The leadless plastic chip carrier according to claim 23, wherein said plurality of layers of metal includes layers of nickel and gold, or silver, or nickel and palladium.